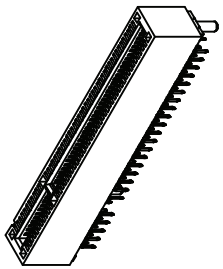


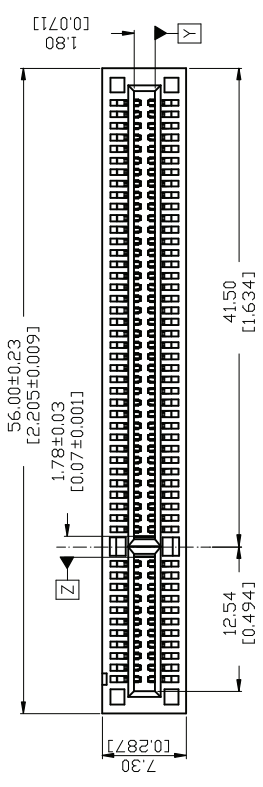
1 2 3 4 5 6 7 8

REV.	ECN	NO.	APPD.
A	BC-07-7068251	C.C. Huang	

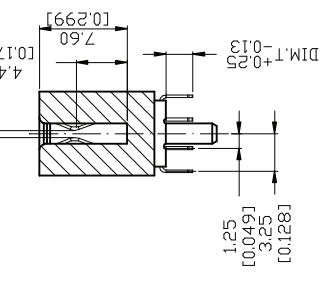
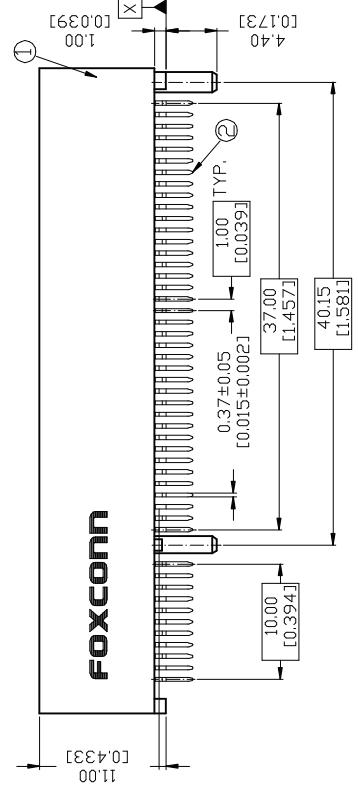


NOTES:

- ELECTRICAL CHARACTERISTICS:
 - CURRENT RATING: 1.1 A MIN., 30°C RISE ABOVE AMBIENT.
 - CONTACT RESISTANCE: 30 MILLIOHMS MAX. INITIAL, 50 MILLIOHMS MAX. AFTER TEST.
 - INSULATION RESISTANCE: 1000 MEGOHMS MIN.
 - DIELECTRICAL WITHSTAND VOLTAGE: 500 V AC MIN. AT SEA LEVEL.
- MECHANICAL CHARACTERISTICS:
 - CONTACT INSERTION FORCE: 1.15 N MAX. PER CONTACT PAIR.
 - CONTACT REMOVAL FORCE: 0.15 N MIN. PER CONTACT PAIR.
 - DURABILITY: 50 MATING AND UNMATING CYCLES.
 - CONTACT RETENTION FORCE: 4.9 N MIN.
- ENVIRONMENTAL CHARACTERISTICS:
 - OPERATING TEMPERATURE RANGE: -40°C TO +105°C.
- PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCTION DETAILS & AVAILABILITY
- RECOMMENDED PROCESS CONDITION: WAVE SOLDER, 260°C, 3~5 S.



ACCEPT 1.57±0.13
[0.062±0.005]
ADD-IN CARD
4.40 [0.173]



PROD. NO.: 2EG 0 *** * - D2LN- **

FIELD PRODUCT SERIES:
2EG= PCI EXPRESS

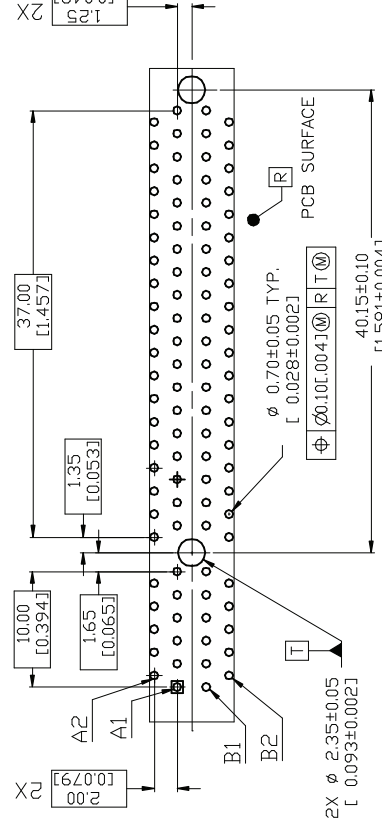
TERMINAL TYPE:
0= VERTICAL TYPE
ND. OF POS. 49= 98 POSITIONS

PLATING TYPE:
DF= LEAD FREE

EXTENSION CODE

CONTACT AREA GOLD PLATING:
1= GOLD FLASH
7= 15μ" GOLD
3= 30μ" GOLD

TAIL LENGTH:
1= 2.30mm
2= 3.10mm



RECOMMENDED PCB LAYOUT

2EG0492*-D2LN-**	3.10[1.22]
2EG0491*-D2LN-**	2.30[0.90]

2	CONTACT	COPPER ALLOY	500μ" MIN. NICKEL PLATING OVER ALL UNPLATED, 1000μ" MIN. TIN PLATING OVER NICKEL AT TAIL, GOLD PLATING ON CONTACT AREA.
1	HOUSING	THERMOPLASTIC UL 94V-0	MOLD BLUE 66IC
ITEM DESCRIPTION		MATERIAL TREATMENT	
X±	X±	UNITS INCH	NAME/INTENDED USE
X±	X±	MAT'L	VERTICAL, T/H 1.00mm PITCH
XX±	XX±	FINISH	PART NOT/INTENDED USE
XXX±	XXX±	QTY	2EG049**~D2LN-**
TITLE		APPD.	C.C. Huang 10/19/07
TITLE		CHKD.	Tin-Suen Liu 10/19/07
TITLE		DR	V.J. Tang 10/19/07
TITLE		DWG. NO.	303-0000-1652
TITLE		SCALE	SHEET 1/2
TITLE		REV.	A



FOXCONN
HON HAI PRECISION IND. CO., LTD.
TAIPEI, TAIWAN, R.O.C.

CUSTOMER DRAWING

PCI Express

303-0000-1652

SCALE SHEET

N/A 1/2 A

1 2 3 4 5 6 7 8